Oncu Akyildiz

List of Publications by Year in Descending Order

18 papers	189 citations	7 h-index	13 g-index
20 ext. papers	213 ext. citations	3.1 avg, IF	2.97 L-index

#	Paper	IF	Citations
18	A process-microstructure finite element simulation framework for predicting phase transformations and microhardness for directed energy deposition of Ti6Al4V. *Additive Manufacturing*, **2020**, 35, 101252	6.1	7
17	Influence of displacement constraints to the surface reconstruction of stressed bicrystal thin films. *Materials Research Express*, **2020**, 7, 026411	1.7	
16	Predicting Microstructure Evolution During Directed Energy Deposition Additive Manufacturing of Ti-6Al-4V. *Journal of Manufacturing Science and Engineering, Transactions of the ASME*, **2018**, 140,	3.3	39
15	Synthesis, characterization and electrochemical performance of Nb doped LiFePO4/C cathodes. *Hittite Journal of Science & Engineering*, **2018**, 5, 49-55	1	2
14	YKSEK KROMLU BEYAZ DKME DEMRLERDE FAZ DENGESNN BENZETM *Uluda University Journal of the Faculty of Engineering*, **2018**, 23, 179-190	0.1	1
13	Thermal Grooving by Surface Diffusion: a Review of Classical Thermo-Kinetics Approach. *Hittite Journal of Science & Engineering*, **2017**, 4, 7-16	1	4
12	The thermodynamic stability of intermediate solid solutions in LiFePO4 nanoparticles. *Journal of Materials Chemistry A*, **2016**, 4, 5436-5447	13	26
11	Particle-size and morphology dependence of the preferred interface orientation in LiFePO4 nano-particles. *Journal of Materials Chemistry A*, **2014**, 2, 15437-15447	13	37
10	Grain boundary grooving in bi-crystal thin films induced by surface drift-diffusion driven by capillary forces and applied uniaxial tensile stresses. *Philosophical Magazine*, **2012**, 92, 804-829	1.6	7
9	Mesoscopic nonequilibrium thermodynamics treatment of the grain boundary thermal grooving induced by the anisotropic surface drift diffusion. *Journal of Materials Science*, **2011**, 46, 6054-6064	4.3	5
8	Grain boundary grooving induced by the anisotropic surface drift diffusion driven by the capillary and electromigration forces: Simulations. *Journal of Applied Physics*, **2011**, 110, 043521	2.5	7
7	Morphological Evolution of Intragranular Void under the Thermal-Stress Gradient Generated by the Steady State Heat Flow in Encapsulated Metallic Films: Special Reference to Flip Chip Solder Joints. *Solid State Phenomena*, **2008**, 139, 151-156	0.4	
6	Morphological evolution of voids by surface drift diffusion driven by the capillary, electromigration, and thermal-stress gradient induced by the steady state heat flow in passivated metallic thin films and flip-chip solder joints. II. Applications. *Journal of Applied Physics*, **2008**, 104, 023522	2.5	4
5	Morphological evolution of voids by surface drift diffusion driven by capillary, electromigration, and thermal-stress gradients induced by steady-state heat flow in passivated metallic thin films and flip chip solder joints. I. Theory. *Journal of Applied Physics*, **2008**, 104, 023521	2.5	12
4	Morphological evolution of tilted grain-boundary thermal grooving by surface diffusion in bicrystal thin solid films having strong anisotropic surface Gibbs free energies. *Journal of Applied Physics*, **2008**, 104, 013518	2.5	4
3	Cathode edge displacement by voiding coupled with grain boundary grooving in bamboo like metallic interconnects by surface drift-diffusion under the capillary and electromigration forces. *International Journal of Solids and Structures*, **2008**, 45, 921-942	3.1	9
2	Computer Simulations on the Grain Boundary Grooving and Cathode Edge Displacement in Bamboo-like Metalic Interconnects. *Materials Research Society Symposia Proceedings*, **2006**, 914, 1		1

List of Publications

1 Grain boundary grooving and cathode voiding in bamboo-like metallic interconnects by surface drift diffusion under the capillary and electromigration forces. *Journal of Applied Physics*, **2005**, 97, 093520 25 23